



RF360
Europe GmbH

Data sheet

SAW RF filter
Short range devices

Series/type: B3905
Ordering code: B39321B3905U510

Date: March 30, 2019

Version: 2.2

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A Qualcomm – TDK Joint Venture

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Table of contents

1	Application	4
2	Features	4
3	Package	5
4	Pin configuration	5
5	Matching circuit	6
6	Characteristics	7
7	Maximum ratings	8
8	Transmission coefficient	9
9	Reflection coefficients	10
10	Packing material	11
11	Marking	13
12	Soldering profile	14
13	ESD protection of SAW filters	15
14	Annotations	16
15	Cautions and warnings	17
16	Important notes	18

1 Application

- Low-loss RF filter for Short range devices
- Impedance transformation from 50 Ω to 200 Ω
- Unbalanced to balanced operation
- Very low insertion attenuation
- Low amplitude ripple
- Usable pass band 1.0 MHz

2 Features

- Package size 3.0 \pm 0.1 mm \times 3.0 \pm 0.1 mm
- Package height 1.1 \pm 0.125 mm
- Package code DCC6D
- Approximate weight 0.04 g
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Lead free soldering compatible with J-STD20C
- Filter surface passivated
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 1 (MSL1)
- AEC-Q200 qualified component family
(Grade 1: -40 $^{\circ}$ C to +125 $^{\circ}$ C)

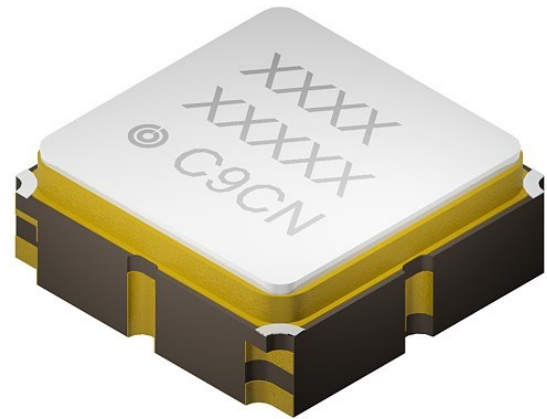
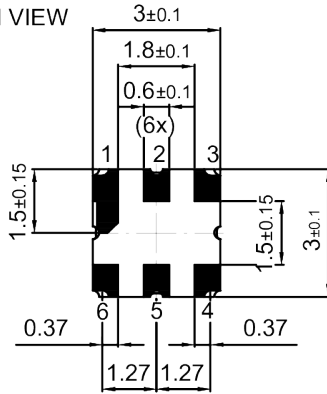


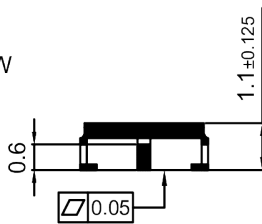
Figure 1: Picture of component with example of product marking.

3 Package

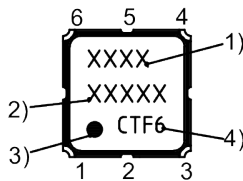
BOTTOM VIEW



SIDE VIEW



TOP VIEW

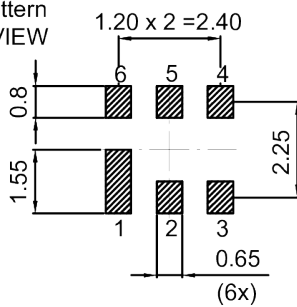


SIDE VIEW



- 1) Device designation
- 2) Last five digits of the lot number
- 3) Marking for pad number 1
- 4) Example of production location and date code

Land pattern
THRU VIEW



Landing pad tolerance -0.02

Figure 2: Drawing of package. See Sec. Package information (p. 17).

4 Pin configuration

- 2 Input (unbalanced)
- 4, 6 Output balanced
- 1, 3, 5 Ground

5 Matching circuit

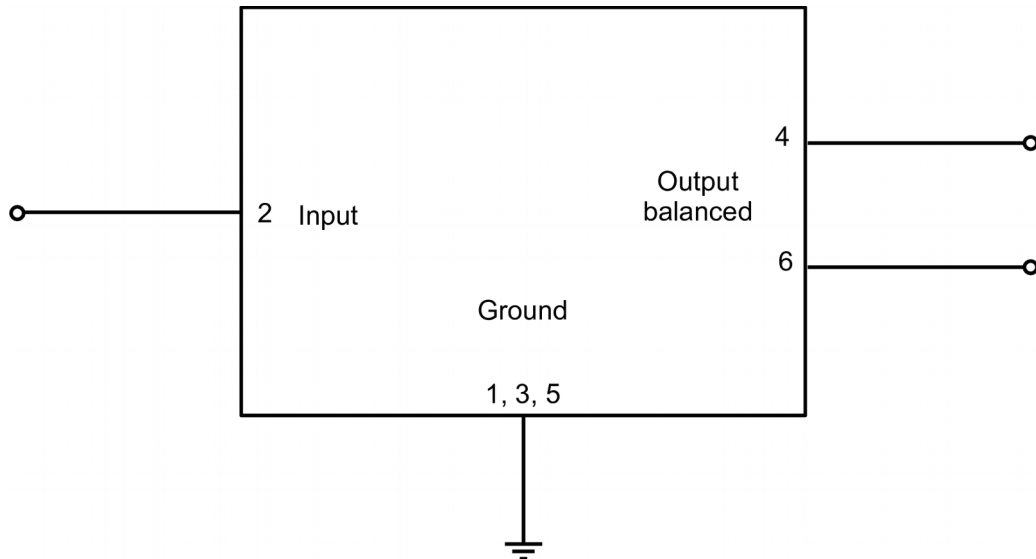


Figure 3: Schematic of matching circuit. No external matching components required.

6 Characteristics

Temperature range for specification	T_{SPEC}	= -40 °C ... +85 °C
Input terminating impedance	Z_{IN}	= 50 Ω
Output terminating impedance	Z_{OUT}	= 200 Ω

Characteristics				min. for T_{SPEC}	typ. @ +25 °C	max. for T_{SPEC}	
Center frequency			f_C	—	315	—	MHz
Maximum insertion attenuation			α_{max}				
	314.5... 315.5	MHz		—	1.3	1.7	dB
Amplitude ripple (p-p)			$\Delta\alpha$				
	314.5... 315.5	MHz		—	0.3	0.8	dB
Maximum VSWR			$VSWR_{max}$				
@ input port	314.5... 315.5	MHz		—	1.2	1.6	
@ output port	314.5... 315.5	MHz		—	1.2	1.6	
Minimum attenuation			α_{min}				
	10... 225	MHz		55	60	—	dB
	225... 285	MHz		50	55	—	dB
	285... 305	MHz		30	35	—	dB
	330... 350	MHz		20	25	—	dB
	350... 450	MHz		45	50	—	dB
	450... 1000	MHz		55	60	—	dB

7 Maximum ratings

Operable temperature	$T_{OP} = -45\text{ °C} \dots +125\text{ °C}$	
Storage temperature	$T_{STG}^{1)} = -45\text{ °C} \dots +125\text{ °C}$	
DC voltage	$ V_{DC} = 6.0\text{ V (max.)}$	
Input power @ input port	$P_{IN} = 10\text{ dBm}$	Source 50Ω, load 200Ω Cw.

¹⁾ Not valid for packaging material. Please refer to definition of Shelf life (p. 16).

8 Transmission coefficient

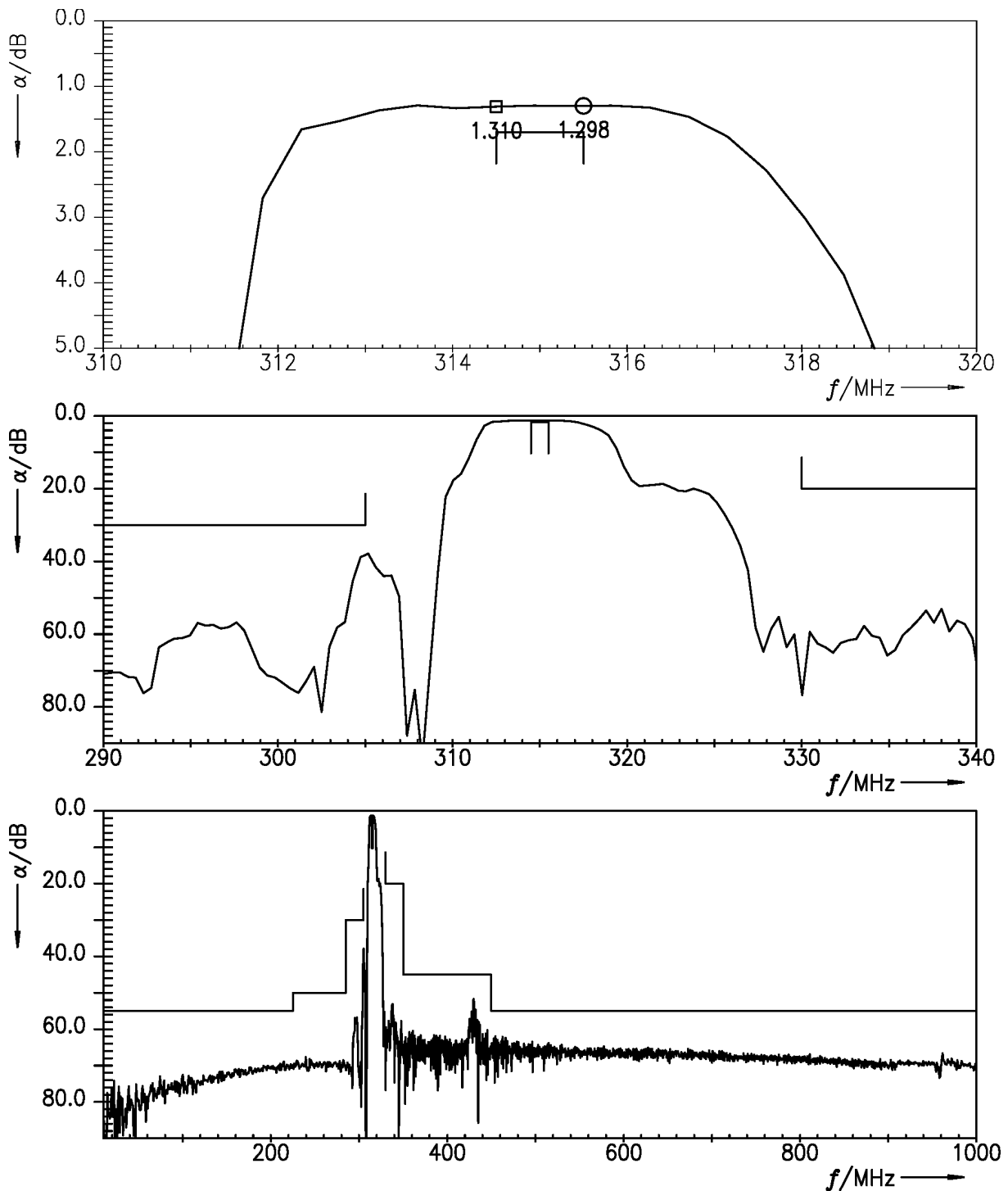


Figure 4: Attenuation .

9 Reflection coefficients

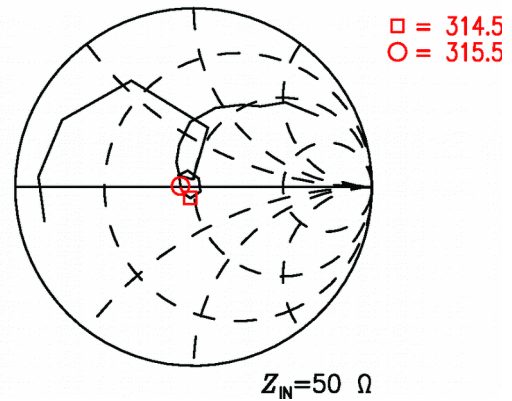
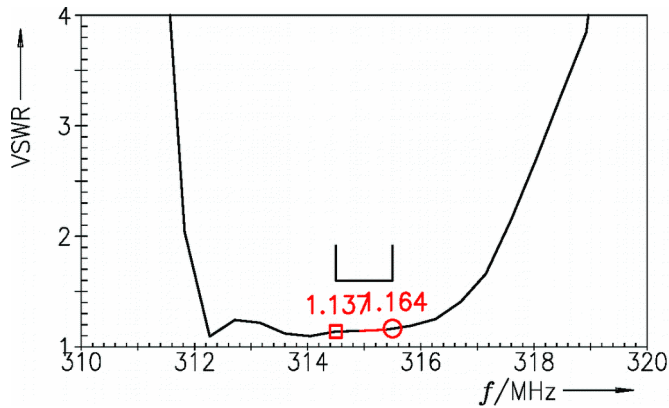


Figure 5: Reflection coefficient at input port.

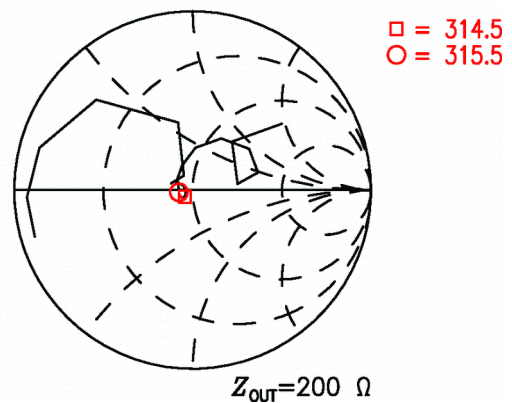
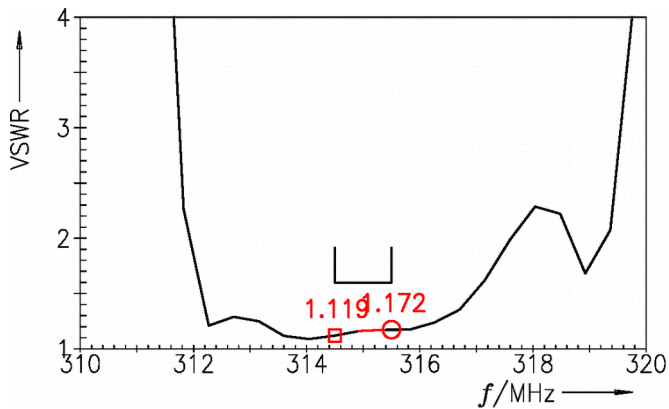


Figure 6: Reflection coefficient at output port.

10 Packing material

10.1 Tape

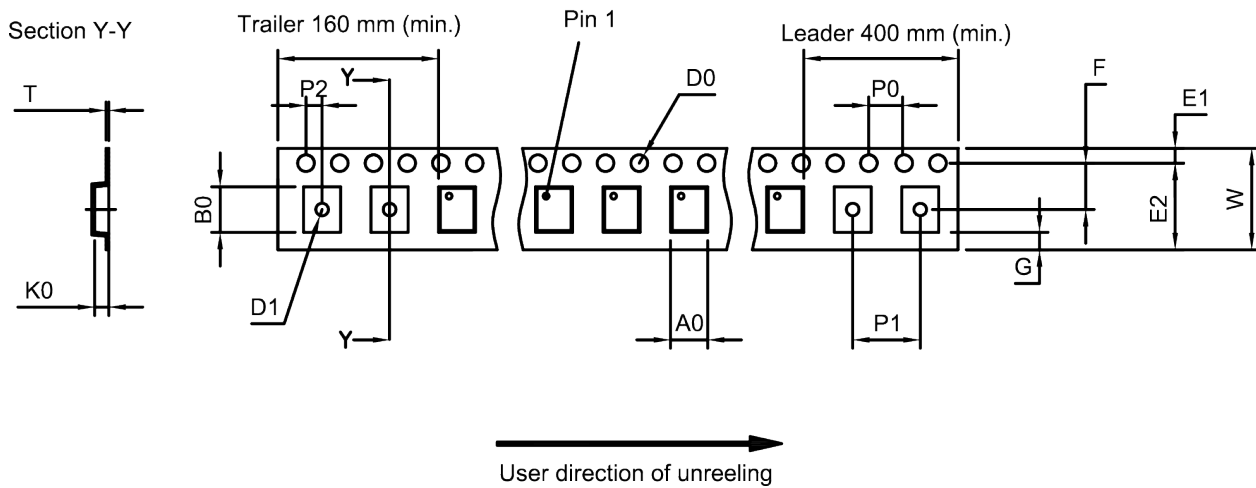


Figure 7: Drawing of tape (first-angle projection) for illustration only and not to scale. The valid tape dimensions are listed in Table 1.

A ₀	3.25±0.1 mm	E ₂	10.25 mm (min.)	P ₁	4.0±0.1 mm
B ₀	3.3±0.1 mm	F	5.5±0.05 mm	P ₂	2.0±0.1 mm
D ₀	1.5+0.1/-0 mm	G	0.75 mm (min.)	T	0.3±0.05 mm
D ₁	1.5 mm (min.)	K ₀	1.5±0.1 mm	W	12.0+0.3/-0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.

10.2 Reel with diameter of 330 mm

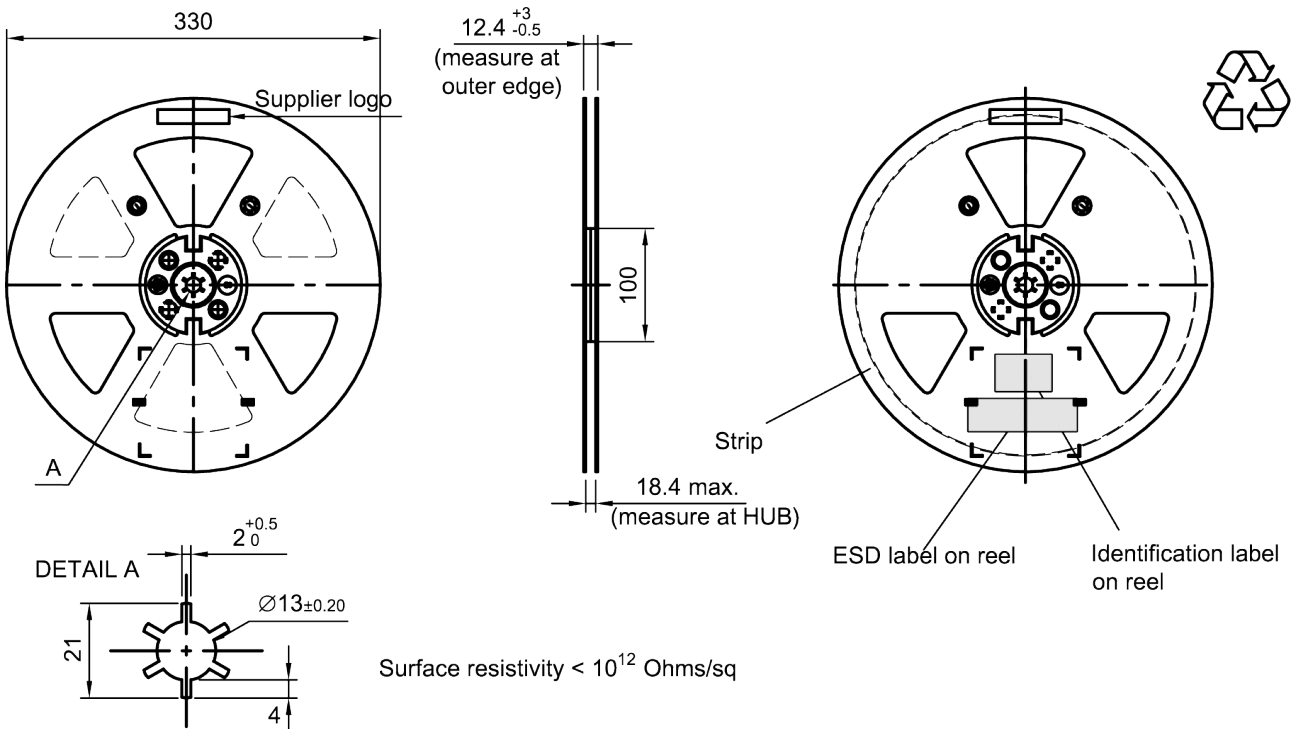
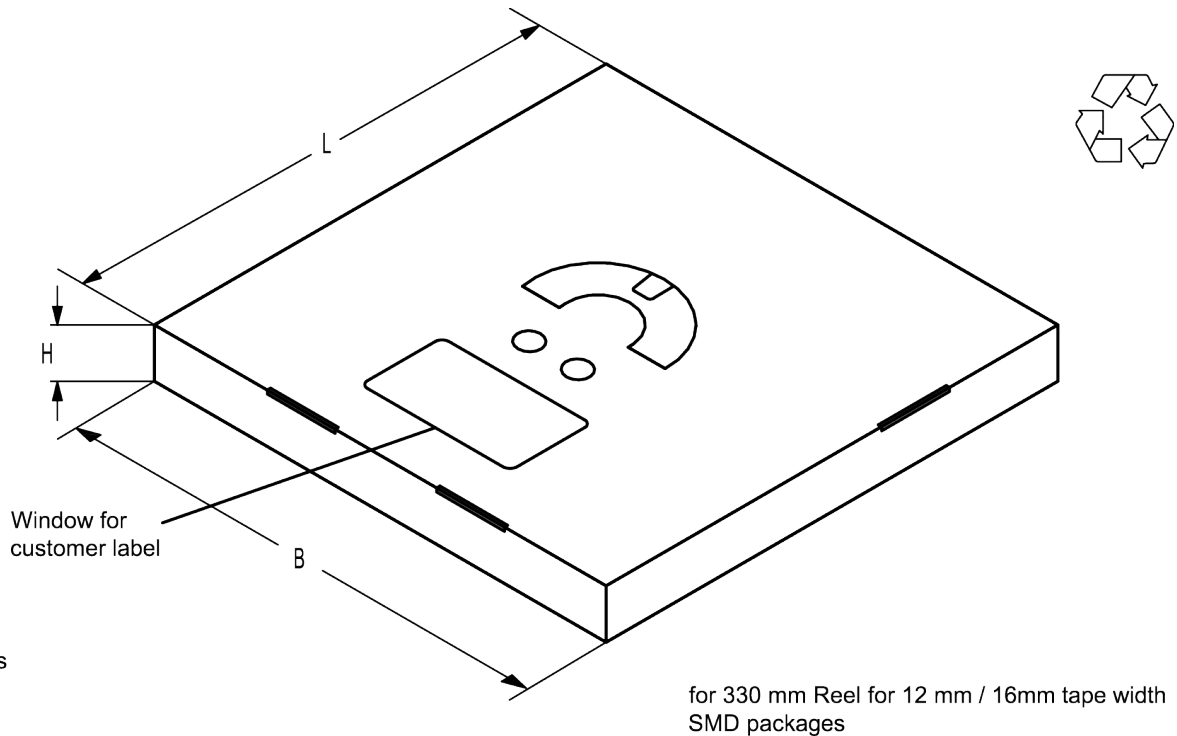


Figure 8: Drawing of reel (first-angle projection) with diameter of 330 mm.



Dimensions

- L = 340
- B = 340
- H = 25

for 330 mm Reel for 12 mm / 16mm tape width SMD packages

Figure 9: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with device designation, lot number, as well as production location and date code.

- Device designation: The 4-character device designation of the ordering code is used for the marking.

Example for 4-character device designation: B3xxxxB1234xxxx

- Lot number: The last 5 digits of the lot number are used for the marking.

Example: 12345

- Production location and date code: The production location is Wuxi (encoded in the first character 'C'). The production date code is encoded in the last three characters according to Table 2.

1 st digit (day)						2 nd digit (year)				3 rd digit (month)			
Day	Code	Day	Code	Day	Code	Year	Code	Year	Code	Month	Code	Month	Code
1	1	11	A	21	M	2010	A	2022	P	Jan	1	Jul	7
2	2	12	B	22	N	2011	B	2023	R	Feb	2	Aug	8
3	3	13	C	23	P	2012	C	2024	S	Mar	3	Sep	9
4	4	14	D	24	R	2013	D	2025	T	Apr	4	Oct	0
5	5	15	E	25	S	2014	E	2026	U	May	5	Nov	N
6	6	16	F	26	T	2015	F	2027	V	Jun	6	Dec	D
7	7	17	H	27	U	2016	H	2028	W				
8	8	18	J	28	V	2017	J	2029	X				
9	9	19	K	29	W	2018	K	2030	Z				
10	0	20	L	30	X	2019	L	2031	A				
				31	Z	2020	M	2032	B				
						2021	N	and so on					

Table 2: Production date code.

Example of how to decode production location and date code:

Code: **C T F 6**

Location: C → Wuxi

Day: T → 26th

Year: F → 2015

Month: 6 → June

12 Soldering profile

The recommended soldering process is in accordance with IEC 60068-2-58 – 3rd edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
T ≥ 255 °C	–
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature T	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

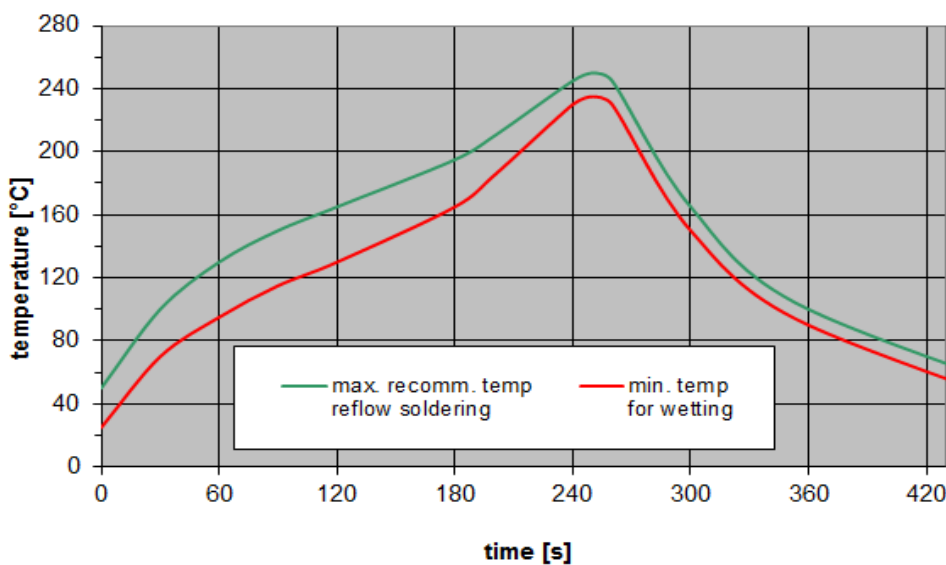


Figure 10: Recommended reflow profile for convection and infrared soldering – lead-free solder.

13 ESD protection of SAW filters

SAW filters are **E**lectro **S**tatic **D**ischarge sensitive devices. To reduce the probability of damages caused by ESD, special matching topologies have to be applied.

In general, “ESD matching” has to be ensured at that filter port, where electrostatic discharge is expected.

Electrostatic discharges predominantly appear at the antenna input of RF receivers. Therefore, only the input matching of the SAW filter has to be designed to short circuit or to block the ESD pulse.

Below three figures show recommended “ESD matching” topologies.

For wide band filters the high-pass ESD matching structure needs to be at least of 3rd order to ensure a proper matching for any impedance value of antenna and SAW filter input. The required component values have to be determined from case to case.

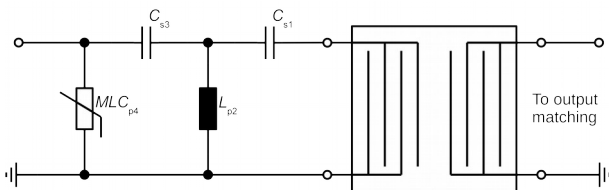


Figure 11: MLC varistor plus ESD matching.

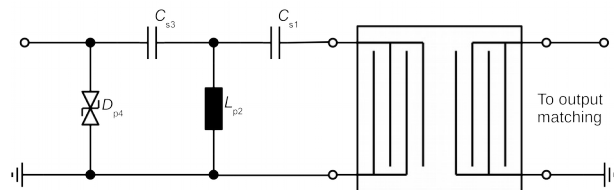


Figure 12: Suppressor diode plus ESD matching.

In cases where minor ESD occur, following simplified “ESD matching” topologies can be used alternatively.

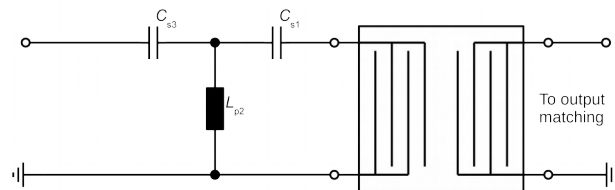


Figure 13: 3rd order high-pass structure for basic ESD protection.

In all three figures the shunt inductor L_{p2} could be replaced by a shorted microstrip with proper length and width. If this configuration is possible depends on the operating frequency and available PCB space.

Effectiveness of the applied ESD protection has to be checked according to relevant industry standards or customer specific requirements.

For further information, please refer to RF360 Application report: “**ESD protection for SAW filters**”. This report can be found under www.rf360jv.com/rke. Click on “Applications Notes”.

14 Annotations

14.1 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

14.2 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local RF360 sales office.

14.3 Shelf life

The shelf life of components is determined by solderability of the package terminals. It is specified as 2 years from manufacturing date assuming the following conditions:

- storage in original packaging and non-aggressive atmosphere,
- storage temperature ranging from $-25\text{ }^{\circ}\text{C}$ to $+40\text{ }^{\circ}\text{C}$, and
- storage humidity with $\leq 75\%$ r.h. mean annual humidity, $\leq 95\%$ r.h. for max. 30 days / year, and no dew condensation.

15 Cautions and warnings

15.1 Display of ordering codes for RF360 products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of RF360, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.rf360jv.com/orderingcodes.

15.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

15.3 Moldability

Before using in overmolding environment, please contact your local RF360 sales office.

15.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on RF360 internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of RF360, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.

16 Important notes

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